

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S5	83	semiconductor and (((chip or die or substrate) with (stack\$3 or mount\$3)) same (soft or flexible or elastic or elastomer or epoxy)) and (package or assembly or housing or module or mcm) and @ad<"20030830" and ((encapsul\$5) with (mold near2 resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 20:18
S13	2149	(257/686 or 257/687).ccls. and @ad<"20030222"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 20:19
S15	951	(257/723).ccls. and @ad<"20030222" and (soft or flexible or elastic or elastomer or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 22:11
S14	1301	(257/686 or 257/687).ccls. and @ad<"20030222" and (soft or flexible or elastic or elastomer or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 22:11
S16	656	(257/723).ccls. and @ad<"20030222" and (soft or flexible or elastic or elastomer or epoxy) not S14	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 22:12
S17	201	(257/787).ccls. and @ad<"20030222" and ((soft or flexible or elastic or elastomer or epoxy) with side)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 22:13
S19	1207	semiconductor and ((chip or die or substrate) with (stack\$3 or mount\$3)) and (package or assembly or housing or module or mcm) and @ad<"20030222" and (encapsul\$5) and ((soft or flexible or elastic or elastomer or epoxy) with (side or sidewall or side adj wall))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 22:36
S10	1269	semiconductor and ((chip or die or substrate) with (stack\$3 or mount\$3)) and (package or assembly or housing or module or mcm) and @ad<"20030830" and (encapsul\$5) and ((soft or flexible or elastic or elastomer or epoxy) with (side or sidewall or side adj wall))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/09 22:36